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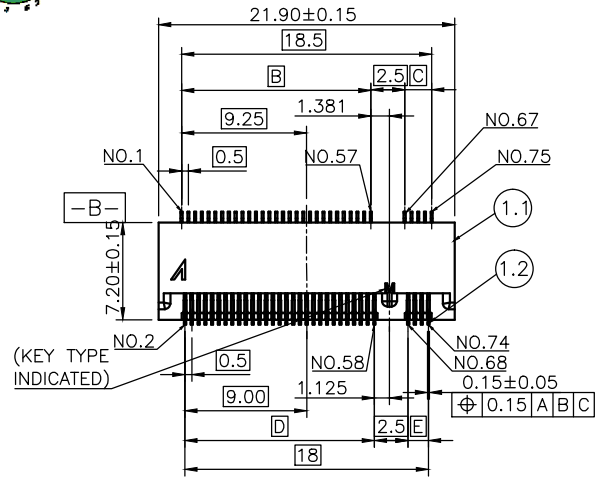
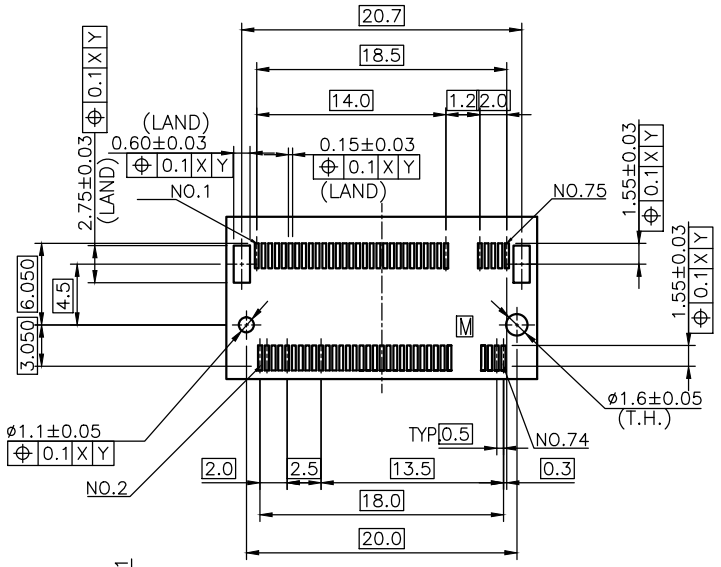




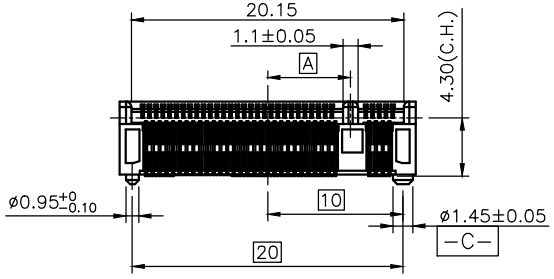
DATUM X IS THE TOP OF SURFACE OF PCB.
RECOMMENDED P.C.B LAYOUT

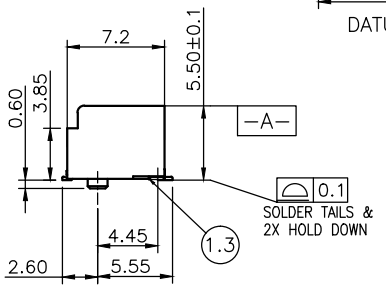
NOTES:
1. MATERIAL:
   1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
   1.2 CONTACT: COPPER ALLOY
   1.3 HOLD DOWN: COPPER ALLOY
2. FINISH:
   2.1 CONTACT:
   GOLD PLATING ON CONTACT AREA.
   GOLD FLASH PLATING ON SOLDER TAILS.
   50~100u" NICKEL UNDERPLATING OVERALL.
   2.2 HOLD DOWN:
   100~200u" MATTE TIN PLATING ON SOLDER TAILS.
   50~100u" NICKEL UNDERPLATNG OVERALL.
3. REFLOW SOLDER CAPABLE TO 260°C ,PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-51743-075XX-XXX
5. PACKAGE PLS. REFER TO 51757-XXXXXX-XX-TRP
6. PART NUMBER

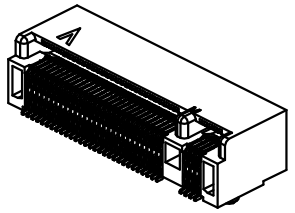
51757-075 0 X-XXX

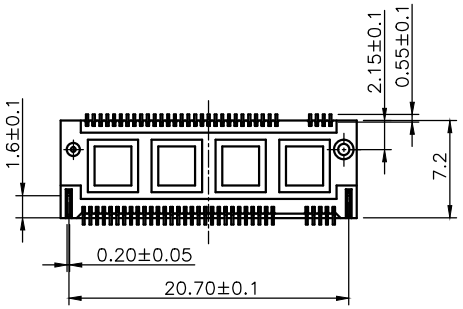
xxx	KEY TYPE	PACKING
012	TYPE M	51757-XXCR-00
DNM	TYPE M	51757-XXCR-05

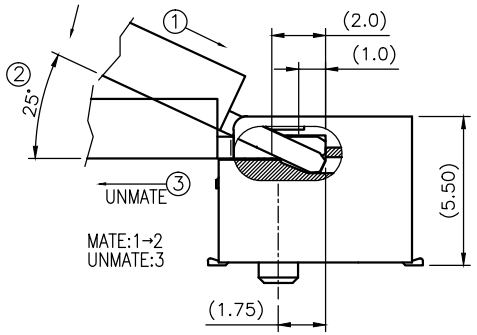
NO OF CKT XXX.CKT
PACKING 0:TAPE&REEL
PLATING C: 15u" GOLD PLATING D: 30u" GOLD PLATING











OPERATION DIRECTION
SCALE 4:1

NO.	PART NUMBER	KEY OPTION	DIM A	DIM B	DIM C	DIM D	DIM E
1	51757-0750X-012	M	6.125	14.0	2.0	14.0	1.5

QUALITY SYMBOLS
MAJOR
CRITICAL

GENERAL TOLERANCES (UNLESS SPECIFIED)
X. ±0.5
.X ±0.25
.XX ±0.15
.XXX ±0.1
ANGLES ±2°

DRAWN BY	YANJINXIU
DATE	22'/08/30
CHECKED BY	XUZHIYONG
DATE	22'/08/30
APPROVED BY	XUZHIYONG
DATE	22'/08/30
UNITS	mm
SIZE	A4
RFQ NO.	N/A
SCALE	2 : 1
SHEET NO.	1 OF 1
REV	C
DWG NO.	51757-0750X-XXX

ACES ELECTRONICS

TITLE: 0.5MM PITCH M.2 CONN. SMT D/R R/A TYPE H=5.50MM

2019.09.02_REV.13

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